

Calendar of Events

March 1, 2022
- May 31, 2022

IMAPS-Czech and Slovak AWOS

TBD

IMAPS-Czech and Slovak is happy to announce the AWOS conference in spring 2022. Further information will be announced shortly.

June 12, 2022
- June 14, 2022

IMAPS-Nordic NordPac 2022

Chalmers University of Technology, Gothenburg, Sweden

TBD

It is our pleasure to announce that the IMAPS Nordic & IEEE EPS Nordic 2022 Conference on Microelectronics Packaging (NordPac) will be held on-site between the 12th and the 14th of June 2022 at Chalmers University of Technology, Gothenburg, Sweden. This is the fourth time that IMAPS Nordic Chapter and IEEE EPS Nordic Chapter jointly organise this event. The NordPac conference is a strong platform that brings together academics, as well as industry leaders, to discuss and debate state-of-the-art and future trends in microelectronics components, packaging, integration, and manufacturing technologies at the Nordic, European and international scale. NordPac provides a perfect opportunity to hear the latest news and developments in the field.

<https://nordic.imapseurope.org/nordpac/>

June 14, 2022
- June 15, 2022

IMAPS-Germany EBL 2022

Schwabenlandhalle, Fellbach

TBD

Intelligent design, intelligent manufacturing, testing and application will be the focus of the upcoming EBL conference, which will take place in Fellbach in June 2022. For this reason, the DVS calls for specialist lectures for the 11th DVS/GMM conference on electronic assemblies and printed circuit boards to be submitted now.

Terms such as “data mining”, “cloud solutions” or “artificial intelligence” have become indispensable in the age of digital transformation. Even in modern assembly technology, huge amounts of data are generated in this way. Whether in development and design, material procurement and storage, during production, quality control, sales and the user – the data volumes are recorded, collected and often processed in real time. But what happens to this data?

These and other questions will be answered at the 11th DVS/GMM Conference in the field of electronic assemblies and printed circuit boards.

June 21, 2022
- June 23, 2022

Advanced SiP Conference

Time TBD
June 21-23, 2022

www.advancedsip.org

DoubleTree by Hilton Sonoma - Wine Country

*The top global event for Advanced System-in-Package technologies!
Combining the 3D ASIP and IMAPS SiP events into an exciting, comprehensive program:
One event covering SiP technology developments, solutions and business trends.*

June 23, 2022
- June 24, 2022

IMAPS-France MiNaPAD 2022

Grenoble, France, at the WTC congress center

TBD

MiNaPAD, the “Micro/Nano-Electronics Packaging & Assembly, Design and Manufacturing Forum” will be held in Grenoble, France, at the WTC congress center from June 23-24, 2022.

MiNaPAD is a 2 days conference with an exhibition. The objective of this event is to reinforce the design community (which constitutes the largest share of the semiconductor community in Europe) and the assembly and packaging community:

*parallel technical sessions
an exhibition
additional technical events*

Grenoble – Europe’s conveniently located technology cluster for semiconductor research, design and manufacturing – easy access to Lyon (1 hour), Geneva (2 hours), Paris (3 hours by high speed train– TGV) airports.

July 5, 2022
- July 6, 2022

IMAPS-UK CPE 2022
University of Warwick, Coventry, UK
TBD

The Centre for Power Electronics (CPE) Annual Conference at the University of Warwick, Coventry, UK on 5-6 July 2022 will bring together the Power Electronics, Machines and Drives Community to review the latest Research and Development that will impact the Electric Revolution. This Conference will feature Invited Keynotes and Presentations from Leading Academics and Industrialists, views of the Future Demands for Power Electronics and Drives and Opportunities for Pursuing a Career in this exciting field.

The Conference will be run over 2 days to provide a comprehensive review of status of Power Electronics Research and Development, including topics selected from:

*Semiconductor and Passive Devices
Packaging and Interconnection
Converters and Drives
Control, Test and Reliability
Power Electronics and Drives Related Applications*

July 13, 2022
- July 15, 2022

IMAPS-Europe CICMT 2022 - Ceramic Interconnect and Ceramic Microsystems Technologies
WKÄ - Veranstaltungszentrum Wirtschaftskammer Österreich, Vienna, Austria
8AM-5PM

cicmt2022@mcc-events.de

The Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT) conference brings together a diverse set of disciplines to share experiences and promote opportunities to accelerate research, development and the application of ceramic interconnect and ceramic microsystems technologies. This international conference features ceramic technology for both microsystems and interconnect applications in a multi-track technical program. The Ceramic Interconnect track focuses on cost-effective and reliable high-performance ceramic interconnect products for extreme environments in the automotive, aerospace, lighting, solar, and communication industries. The Ceramic Microsystems track focuses on emerging applications and new products that exploit the ability of 3D ceramic structures to integrate interconnect/packaging with microfluidic, optical, micro-reactor and sensing functions. Multilayer ceramic, thin film, tape casting, thick film hybrid, direct write, and rapid prototyping technologies are common to both tracks, with emphasis on materials, processes, prototype development, advanced design, and application opportunities.

July 18, 2022
- July 20, 2022

HiTen 2022
TBD

*International Conference and Exhibition on
High Temperature Electronics Network (HiTEN 2022)
July 18-20, 2022
St. Anne's College in the University of Oxford
Oxford, United Kingdom
www.imaps.org/hiten*

Abstracts Due: March 2, 2022

Conference Chairs:

*Colin Johnston
Oxford University
colin.johnston@materials.ox.ac.uk
F. Patrick McCluskey
University of Maryland
mcclupa@umd.edu*

HiTEN Conference Focus:

The objective of the HiTEN Conference is to have a unique forum that brings together researchers and practitioners in academia and industry from all over the world. All styles of practical high temperature electronics design and implementation approaches are encouraged, along with a variety of high temperature application areas. Today the main semiconductor focus of HiTEN is silicon and silicon on insulator (SOI). Although, HiTEN is not simply a semiconductor focused network. HiTEN provides a conduit for the exchange and dissemination of information on all aspects of high temperature electronics. It is a global network with users, suppliers, developers and fundamental researchers dealing in all aspects of High Temperature Electronics. HiTEN 2022 will include a new Invited Session on the eHarsh Project by Fraunhofer.

Abstracts are being requested in the following areas:

*Applications in the Aerospace, Automotive, Oil & Gas, and Geothermal Industries
Devices and applications
Novel devices
ASICs
Memories
Passive components
Power devices*

MEMS Devices
Sensors
Contacts and metallizations
Semiconductor materials
Materials
Packaging and interconnects
Sealants, adhesives, solders
Reliability and failure mechanisms
Lifetime predictions
Accelerated life testing
Testing

Those wishing to present and publish a paper at the HiTEN 2022 Conference must submit a ~500 word abstract electronically on/before MARCH 2, 2022, using the on-line submittal form at: www.imaps.org/hiten. All abstracts submitted should represent original, previously unpublished work. All speakers are required to pay a reduced registration fee. If your abstract is selected, you will be asked to follow the speaker timeline: - Speaker Acceptance Email (April 1, 2022); - Final Manuscript due for Proceedings (June 1, 2022); - Speaker Registration complete (June 1, 2022); - BIO Submitted (July 1, 2022); Slides/Presentation for session presentation (on/before July 17, 2022); and - Slides/Presentation file to distribute to registrants post-conference (on/before July 25, 2022).

The HiTEN Proceedings papers will be ARCHIVED into IMAPS online research portal/library, IMAPSource® - www.imapsource.org. IMAPSource® currently features all of IMAPS proceedings, journal papers, magazines, and other conference publications back to 2010. This portal is a fully searchable, user and Google Scholar-friendly database. The software allows for fully exportable citations, improved keyword and Boolean search functionality and customizable alerts, among many other features. The library is indexed by Google Scholar and many key scientific engines/indexes, and growing each day. Please visit www.imapsource.org and search. HiTEC/HiTEN Proceedings can be found in our conference section: <http://www.imapsource.org/loi/apap>.

Accepted papers may also be considered for publication in the IMAPS Journal of Microelectronics and Electronic Packaging. If you need assistance with the on-line submission form, please email info@imaps.org.

Students wishing to present at the HiTEN Conference must also submit a ~500 word abstract electronically and must check the "YES, I'm a full-time Student" button at the bottom of the submission page after you enter your abstract text in order to be considered for the student competition award.

September 13, 2022
- September 16, 2022

IMAPS-Europe ESTC 2022

Sibiu, Rumänien

TBD

The Electronics System-Integration Technology Conference (ESTC) is the premier international event in the field of electronics packaging and system integration. The conference is organized every two years in Europe and is supported by IEEE-EPS in association with IMAPS-Europe. The 9th ESTC will be taking place in Sibiu, Romania. Placed in the middle of Romania, surrounded by the high Carpathian Mountains and Cibi river, Sibiu is a citadel of the European electronics industry and represents a place where culture, landscape, gastronomy and profession merge in a friendly pleasant environment.

The ESTC 2022 seeks original, noncommercial papers describing research and innovations in all areas of electronics packaging and system integration. Authors are invited to submit an abstract describing recent work. Abstracts must detail the objectives of the work presented and demonstrate new results.

Proposed topics include:

- *Advanced packaging*
- *Materials for interconnects and packaging*
- *Optoelectronic systems packaging*
- *Assembly and manufacturing technologies*
- *Design tools and modeling*
- *Power electronics system packaging*
- *Advanced technologies for emerging systems*
- *Reliability and quality of electronic devices and systems*
- *Flexible, printed and hybrid electronics*
- *RF, mm-wave and THz systems packaging*
- *Global education for electronics*

September 26, 2022
- September 29, 2022

IMAPS-Europe ESREF 2022

H4 Hotel Berlin, Deutschland

TBD

ESREF 2022, the 33rd European Symposium on Reliability of Electron Devices, Failure Physics and Analysis, will take place in Berlin (Germany) from September 26-29, 2022 at the H4 Hotel Berlin Alexanderplatz.

This international symposium continues to focus on the newest developments and future prospects for quality and reliability management of materials, devices, and circuits for micro-, nano-, and optoelectronics. It provides a European forum for all aspects of reliability management and innovative analytical techniques for present and future electronic applications.

The conference will include the following tracks:

*Assessment Techniques and Methods for Devices and Systems
Semiconductor and Nanoelectronics Technologies
Progress in Failure Analysis Methods
Microwave Devices and Circuits
Packaging and Assemblies
Power Devices and Systems
Photonics Devices
MEMS and Sensors
Extreme Environments and Radiation*

Deadline for the four page abstract submission is March 20, 2022. Registration fees for presenting authors are expected to be about 650 euros. Authors must be present on site and give a presentation in person. Fees for regular participants will be 950 euros (on-site) or 500 euros (online). The aim is to have a face-to-face event. The online format is intended only as a fallback option.

October 1, 2022
- December 31, 2022

IMAPS-Hungary Girls Day at BME VIK and ETT

Budapest, Hungary

TBD

IMAPS-Hungary is happy to announce its Girls Day at the BME VIK faculty and the ETT department during the third quarter of 2022. Further information will be announced soon.

Location: Budapest, Hungary

October 3, 2022
- October 6, 2022

55th International Symposium on Microelectronics (IMAPS 2022)

Hynes Convention Center

900 Boylston Street

Boston, MA 02115

07:00 AM - 05:00 PM EST

IMAPS HQ, 919-293-5000

info@imaps.org

October 3, 2022

IMAPS Workshop on Strategies to Revitalize the On-Shore Packaging and Assembly Defense

Hynes Convention Center

08:00 AM - 05:30 PM EST

General Co-Chairs:

Jim Will, SkyWater Technology; Chris Riso, Booz Allen Hamilton Inc.

Speakers by Invitation Only – Program Details Soon

Overview: The International Microelectronics Assembly and Packaging Society (IMAPS) will host a one-day Workshop to discuss and promote strategies to improve On-Shore Packaging and Assembly Capabilities on Monday, October 3, 2022, at the Hynes Convention Center, Boston, Massachusetts. The mission of this workshop is to engage our workforce community to identify solutions, which address US Government and Defense requirements, critical to the onshoring of the microelectronic assembly and packaging supply chain. The workshop will feature a SHIP keynote speaker and SHIP program speakers, plus several breakout sessions with speakers focused on: Manufacturing, Assembly, Substrates & Materials, Enabling & Disruptive Technologies, Reliability, the Chipllet Ecosystem, and Workforce Development.

All workshop attendees are invited to join the WELCOME RECEPTION for the IMAPS 2022 Symposium on Microelectronics at the conclusion of the workshop!

October 28, 2022

- October 30, 2022

IMAPS-Czech and Slovak IMAPS Flash Conference 2022

Brno University of Technology

TBD

With pleasure we invite all prospective authors to participate in IMAPS-Czech and Slovak 8th annual IMAPS flash 2022 conference, which will be held by the end of October 2022 at Brno University of Technology, FEEC, Department of Microelectronics.

November 1, 2022

- November 30, 2022

IMAPS-Hungary Open Laboratory Event

Budapest, Hungary

TBD

IMAPS-Hungary is happy to announce its open laboratory event for students during November 2022. Further information about the event will be announced soon.

November 1, 2022

- November 30, 2022

SEMICON Europa

TBD

SEMICON Europa is the largest European trade fair for microelectronics. It is where market leaders along the entire supply chain of development and manufacturing meet.

The SEMICON Europa program addresses the important issues and challenges facing the microelectronics industry and offers participants the opportunity to exchange ideas and showcase technical innovations. More information about SEMICON Europa will follow shortly.

November 24, 2022

IMAPS-France Power Electronics Workshop

TBD

IMAPS is pleased to inform you about the next POWER ELECTRONICS workshop on 24th November 2022.

The 13th edition will be organized in Tours and in GREMAN amphitheater as previous years.

Call for papers, deadline submission is July the 25th

We would like to remind you a one-day table top exhibition.

www.france.imapseurope.org

March 8, 2023
- March 9, 2023

**16th European Advanced Technology Workshop ON MICROPACKAGING AND THERMAL MANAGEMENT
POITIERS FUTUROSCOPE**

TBD

IMAPS is pleased to inform you about the next THERMAL workshop on 8th and 9th March 2023. The newness is the location of 16th edition will be organized in Futuroscope of Poitiers.

March 13, 2023
- March 16, 2023

Device Packaging Conference 2023

WeKoPa Resort

TBD

www.devicepackaging.org

September 11, 2023
- September 14, 2023

EMPC 2023

Genome Centre

TBD

24th European Microelectronics Packaging Conference

EMPC 2023 is scheduled to take place at the Genome Centre, Cambridge, United Kingdom on the 11th to 14th of September 2023.

The event will present the best of microelectronics packaging and interconnection technologies, providing world-class coverage of technological innovation in the microelectronics and packaging field with contributions from both industry and academia.

October 2, 2023
- October 5, 2023

IMAPS 2023 San Diego Symposium

TBD

IMAPS 2023 San Diego Symposium

Town and Country Hotel in San Diego, 500 Hotel Circle North, San Diego CA 92108